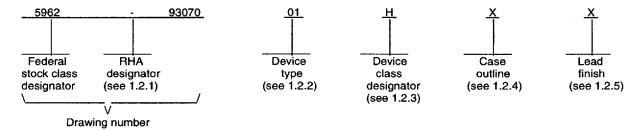
								R	EVISI	ONS										
LTR					D	ESCR	IPTIOI	N					DA	TE (Y	R-MO-D	(A)		APPR	OVED)
A	Char	nges	in a	ccor	dano	ce wi	th N	IOR 5	962-	R139	-95.		9!	5-05	-11	K. Cottongim		n		
В	case top 1; of	Corrected figure 1 to move the side view of case outlines X and Z to the right side of the top view for the correct orientation. Figure 1; removed the min limit for the D dimension of 2.880 inches (73.15 mm) for the case outline Zsld								К.	Cotto	ongin	n							
REV																				
SHEET																				
SHEET REV SHEET																				
REV SHEET REV SHEET REV STATI				REV			В	В	В	В	В	В	В	В	В	В	В	В	В	E
SHEET REV SHEET REV STATE				SHE			B 1	B 2	В 3	B 4	5	6 DEFEI	7 NSE S	8 UPPL	9 Y CEI	10	11 COLU	12 IMBUS	13	┝
SHEET REV SHEET REV STATION SHEET PMIC N/A STA	ANDA OCIR	CUI	F	PREI Steve	EET	ncan BY		 	 	 	5	6 DEFEI	7 NSE S	8 UPPL	9 Y CEI	10	11 COLU	12 IMBUS	13	┝
SHEET REV SHEET PMIC N/A STA MICRO DR THIS DRAW	ANDA OCIR AWIN VING IS A USE BY	CUI" IG VAILAE		SHE PREI Steve CHE Mich	PARED L. Du CKED nael John	ncan BY nes	1	 	 	4 MIC	5 ROC	6 DEFEI	7 NSE S COLUM	8 UPPL	9 Y CEI , OHIO	10 NTER 0 432	11 COLU 16-500	12 IMBUS	13	1
SHEET REV SHEET REV STATE OF SHEET PMIC N/A STA MICRE DR THIS DRAW FOR	ANDA OCIR AWIN VING IS A USE BY USE BY USE BY USE BY ENCIES (CUITALAE ALL ITS OF THE	BLE	SHE PREI Steve CHE Mich	PAREC L. Du CKED nael Jon ROVEC	BY nes D BY Cottons	1 gim	2	 	MIC CHA	5 ROCI	6 DEFEI	7 NSE S COLUM	8 UPPL MBUS YBRII	9 Y CEI , OHIO	NTER O 432 NEAR,	11 COLU 16-500	12 IMBUS	13 SING	E 1

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DISTRIBUTION STATEMENT A. Approved for public release; distribution is unlimited.

5962-E435-98

1. SCOPE

- 1.1 <u>Scope</u>. This drawing documents five product assurance classes, class D (lowest reliability), class E, (exceptions), class G (lowest high reliability), class H (high reliability), and class K, (highest reliability) and a choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN). When available, a choice of radiation hardness assurance levels are reflected in the PIN.
 - 1.2 PIN. The PIN shall be as shown in the following example:



- 1.2.1 <u>Radiation hardness assurance (RHA) designator</u>. Device classes H and K RHA marked devices shall meet the MIL-PRF-38534 specified RHA levels and shall be marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.
 - 1.2.2 Device type(s). The device type(s) shall identify the circuit function as follows:

Device type	Generic number	Circuit function
01	MTR2815S/883, MTR2815SF/883	DC/DC converter, 30 W, 15 V output

1.2.3 <u>Device class designator</u>. This device class designator shall be a single letter identifying the product assurance level as follows:

Device class

Device performance documentation

D, E, G, H, or K

Certification and qualification to MIL-PRF-38534

1.2.4 <u>Case outline(s)</u>. The case outline(s) shall be as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	<u>Terminals</u>	Package style
X	See figure 1	10	Dual-in-line
Z	See figure 1	10	Flange mount

1.2.5 Lead finish. The lead finish shall be as specified in MIL-PRF-38534.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-93070
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000		REVISION LEVEL B	SHEET 2

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1.3 Absolute maximum ratings. 1/								
Input voltage range Power dissipation (PD) Output power Lead soldering temperature (10 seconds) Storage temperature range	12 W 30.9 W +300°C							
1.4 Recommended operating conditions.								
Input voltage range+16 V dc to +40 V dc Case operating temperature range (T _C)55°C to +125°C								
2. APPLICABLE DOCUMENTS								
of this drawing to the extent specified herein. Unless otherwise :	2.1 Government specification, standards, and handbook. The following specification, standards, and handbook form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those listed in the issue of the Department of Defense Index of Specifications and Standards (DoDISS) and supplement thereto, cited in the							
SPECIFICATION								
DEPARTMENT OF DEFENSE								
MIL-PRF-38534 - Hybrid Microcircuits, General Specific	ation for.							
STANDARDS		•						
DEPARTMENT OF DEFENSE								
MIL-STD-883 - Test Methods and Procedures for Micr MIL-STD-973 - Configuration Management. MIL-STD-1835 - Microcircuit Case Outlines.	oelectronics.							
HANDBOOK								
DEPARTMENT OF DEFENSE								
MIL-HDBK-780 - Standard Microcircuit Drawings.								
(Unless otherwise indicated, copies of the specification, stand Document Order Desk, 700 Robbins Avenue, Building 4D, Phila	lards, and handbo delphia, PA 1911	ook are available from the S 1-5094.)	standardization					
2.2 Order of precedence. In the event of a conflict between the of this drawing takes precedence. Nothing in this document, ho specific exemption has been obtained.	he text of this dravever, supersede	wing and the references cites applicable laws and regu	ed herein, the text lations unless a					
T/ Stresses above the absolute maximum rating may cause per maximum levels may degrade performance and affect relial	ermanent damage bility.	e to the device. Extended o	peration at the					
STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-93070					
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3. REQUIREMENTS

- 3.1 Item requirements. The individual item performance requirements for device classes D, E, G, H, and K shall be in accordance with MIL-PRF-38534. Compliance with MIL-PRF-38534 may include the performance of all tests herein or as designated in the device manufacturer's Quality Management (QM) plan or as designated for the applicable device class. Therefore, the tests and inspections herein may not be performed for the applicable device class (see MIL-PRF-38534). Futhermore, the manufacturers may take exceptions or use alternate methods to the tests and inspections herein and not perform them. However, the performance requirements as defined in MIL-PRF-38534 shall be met for the applicable device class
- 3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38534 and herein.
 - 3.2.1 Case outline(s). The case outline(s) shall be in accordance with 1.2.4 herein and figure 1.
 - 3.2.2 Terminal connections. The terminal connections shall be as specified on figure 2.
- 3.3 <u>Electrical performance characteristics</u>. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full specified operating temperature range.
- 3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are defined in table I.
- 3.5 <u>Marking of Device(s)</u>. Marking of device(s) shall be in accordance with MIL-PRF-38534. The device shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's vendor similar PIN may also be marked as listed in QML-38534.
- 3.6 <u>Data</u>. In addition to the general performance requirements of MIL-PRF-38534, the manufacturer of the device described herein shall maintain the electrical test data (variables format) from the initial quality conformance inspection group A lot sample, for each device type listed herein. Also, the data should include a summary of all parameters manually tested, and for those which, if any, are guaranteed. This data shall be maintained under document revision level control by the manufacturer and be made available to the preparing activity (DSCC-VA) upon request.
- 3.7 <u>Certificate of compliance</u>. A certificate of compliance shall be required from a manufacturer in order to supply to this drawing. The certificate of compliance (original copy) submitted to DSCC-VA shall affirm that the manufacturer's product meets the performance requirements of MIL-PRF-38534 and herein.
- 3.8 <u>Certificate of conformance</u>. A certificate of conformance as required in MIL-PRF-38534 shall be provided with each lot of microcircuits delivered to this drawing.

4. QUALITY ASSURANCE PROVISIONS

4.1 <u>Sampling and inspection</u>. Sampling and inspection procedures shall be in accordance with MIL-PRF-38534 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein.

STANDARD
MICROCIRCUIT DRAWING
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COLUMBUS, OHIO 43216-5000

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Output current Output ripple voltage VRIF Line regulation VRL Load regulation Input current Input ripple current Input ripple current Efficiency Eff Isolation Iso Capacitive load 1/2/ CL)T	-55°C ≤ T _C ≤ +125°C V _{IN} = 28 V dc ±.5 V dc no external sync, C _L = 0 unless otherwise specifie		type			Unit
Output current Output ripple voltage VRIF Line regulation VRL Load regulation VRL Input current Input ripple current Input ripple current Efficiency Eff Isolation Iso)T		d		Min	Max	
Output ripple voltage VRIF Line regulation VRL Load regulation VRL Input current Input ripple current Input ripple current Isolation Isolation Capacitive load 1/2/ CL		I _{OUT} = 2.0 A dc	1	01	14.85	15.15	V dc
Output ripple voltage VRIF Line regulation VRL Load regulation VRL Input current Input ripple current Input ripple current Efficiency Eff Isolation ISO Capacitive load 1/2/ CL			2, 3		14.55	15.45	
Line regulation VRL Load regulation VRL Input current IN Input ripple current Fff Efficiency Eff Isolation ISO Capacitive load 1/2/ CL	Γ	V _{IN} = 16 V dc, 28 V dc, and 40 V dc	1, 2, 3		0.0	2000	mA
Load regulation VRL Input current IN Input ripple current IRIP Efficiency Eff Isolation ISO Capacitive load 1/2/ CL		I _{OUT} = 2.0 A, B.W. = 10 kHz to 2 MHz	1			40_	mV p-p
Load regulation VRL Input current IN Input ripple current IRIP Efficiency Eff Isolation ISO Capacitive load 1/2/ CL		B.W. = 10 KHZ to 2 MHZ	2, 3			90	
Input current Input ripple current Efficiency Eff Isolation ISO Capacitive load 1/2/ CL	INE	V _{IN} = 16 V dc to 40 V dc, I _{OUT} = 2.0 A	1, 2, 3			50	mV
Input ripple current IRIP Efficiency Eff Isolation ISO Capacitive load 1/2/ CL	.OAD	I _{OUT} = 0 to 2.0 A	1, 2, 3			50	
Efficiency Eff Isolation ISO Capacitive load 1/2/ CL	current I_{IN} $I_{OUT} = 0$, inhibit $(pin 2) = 0$		1, 2, 3			8	mA
Efficiency Eff Isolation ISO Capacitive load 1/2/ CL		l _{OUT} = 0, inhibit (pin 2) open				75	
Isolation ISO Capacitive load 1/2/ CL	•	I _{OUT} = 2.0 A, B.W. = 10 kHz to 10 MHz	1, 2, 3			50	тА р-р
Capacitive load 1/2/ C _L		I _{OUT} = 2.0 A	1	_	81		%
Capacitive load 1/2/ C _L			2, 3		78		
		Input to output or any pin to case (except pins 7 and 8) at 500 V dc			100		мΩ
See footnotes at end of table.	•••	No effect on dc performar	nce 4			3000	μF
				1	I		
STAN MICROCIRCU			SIZE A				5962-9307
DEFENSE SUPPLY C COLUMBUS, O		ER COLUMBUS		REVISI	ION LEVE	L	SHEET

	TAE	BLE I. <u>Electrical performan</u>	ce characteristics	- Continu	ed.		
Test	Test Symbol Conditions -55°C < T _C < +125°C V _{IN} = 28 V dc ±.5 V dc no external sync, C _L = 0 unless otherwise specified		Group A subgroups	Device type	Limits		Unit
			ed		Min	Мах	
Power dissipation, load fault	PD	Short circuit	2, 3	01		10	w
Switching frequency	F _S	I _{OUT} = 2.0 A	4, 5, 6	•	550	650	kHz
External sync range 3/	FSYNC	I _{OUT} = 2.0 A, TTL level t	0 4, 5, 6		500	675	kHz
Output response to step transient load changes 4/	V _{TLOAD}	DAD 50 percent load to/from 100 percent load			-500	+500	mV pk
Recovery time, step transient load changes 2/4/5/	TT _{LOAD}	50 percent load to/from 100 percent load			,	200	μs
Output response to transient step line changes 2/6/	ransient step line to 40 V dc, I				-600	+600	mV pk
		Input step from 40 V dc to 16 V dc, I _{OUT} = 2.0 A			-600	+600	
Recovery time, transient step line changes 2/5/	TTLINE	Input step from 16 V dc to 40 V dc, I _{OUT} = 2.0 A	5			300	μs
		Input step from 40 V dc to 16 V dc, I _{OUT} = 2.0 A				300	
Turn-on overshoot 2/	VtonOS	I _{OUT} = 2.0 A				150	mV pk
Turn-on delay 7/	TonD	I _{OUT} = 2.0 A			5	ms	
Load fault recovery Tr_{LF} $I_{OUT} = 2.0 \text{ A}$					5		
See footnotes at top of ne	ext page.			ļ	,	1	
	STANDARD CIRCUIT DR	1	SIZE A				5962-93070
MICROCIRCUIT DRAWING DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000				REVISIO	N LEVEL B	=	SHEET 6

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TABLE I. <u>Electrical performance characteristics</u> - Continued.

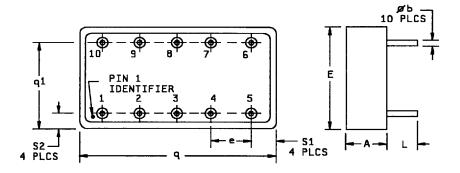
- 1/ Capacitive load may be any value from 0 to the maximum limit without compromising dc performance.
- 2/ Parameter shall be tested as part of design characterization and after design or process changes; therefore, the parameter shall be guaranteed to the limits specified in table I.
- 3/ A TTL level waveform (V_{IH} = 4.5 V minimum, V_{IL} = .8 V maximum) with a 50 percent ±10 percent duty cycle applied to sync input pin (pin 9) within the sync range frequency shall cause the converter's switching frequency to become synchronous with the frequency applied to the sync input pin (pin 9).
- 4/ Load step transition time 10 microseconds maximum.
- 5/ Recovery time is measured from the initiation of the transient to where V_{OUT} has returned to within ±1 percent of V_{OUT} final value.
- 6/ Input step transition time 10 and 50 microseconds.
- 7/ Turn-on delay time measurement is either for a step application of power at the input or the removal of a ground signal from the inhibit pin (pin 2) while power is applied to the input.

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Case X



Symbol	Millin	neters	Inc	ches	
	Min	Max	Min	Max	
Α		10.16		.400	
фb	0.89	1.14	0.035	0.045	
е	10.10	6 BSC	.400 BSC		
E	28.07	28.32	1.105	1.115	
L	6.09	6.60	0.240	0.260	
q		53.21		2.095	
q1	24.26 BSC		0.955 BSC		
S1	6.22 BSC		0.245 BSC		
S2	3.94	BSC	0.155 BSC		

NOTES:

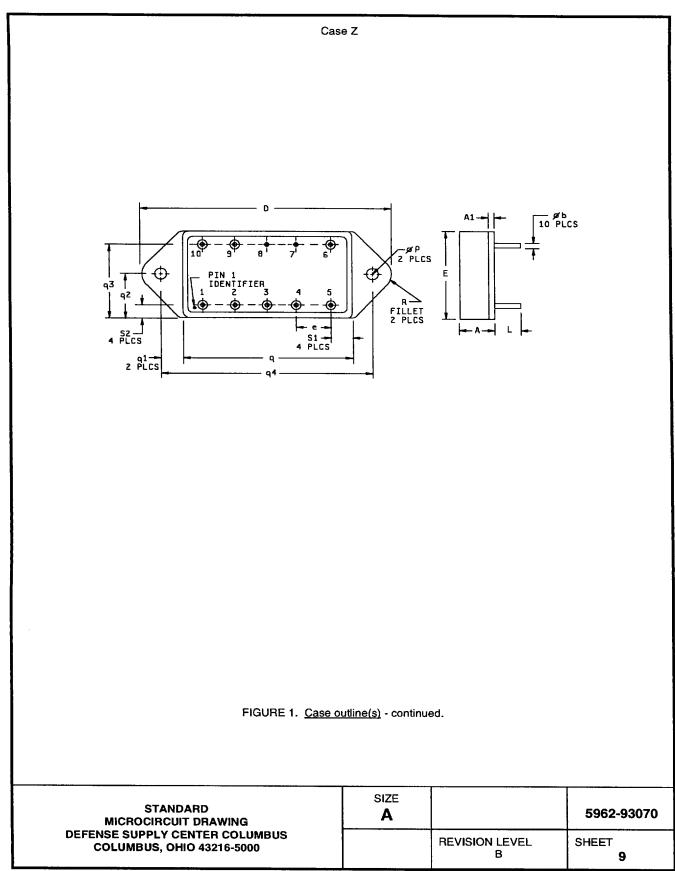
- 1. The case outline X was originally designed using the inch-pound units of measurement, in the event of conflict between the metric and inch-pound units, the inch-pound units shall take precedence.
- 2. Device weight: 52 grams.

FIGURE 1. Case outline(s).

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Case Z - Continued

Symbol	Millin	neters	Inc	ches	
	Min	Max	Min	Max	
Α		10.16		.400	
A1	1.27	1.78	0.05	0.07	
фЬ	0.89	1.14	0.035	0.045	
D		73.66		2.900	
е	10.16	BSC	.400	BSC	
E	28.07	28.32	1.105	1.115	
L	6.09	6.60	0.240	0.260	
фр	3.99	4.19	0.157	0.165	
q	53.08	BSC	2.090 BSC		
q1	5.84	BSC	0.230 BSC		
q2	14.10	BSC	0.555 BSC		
q3	24.26	BSC	0.955 BSC		
q4	64.52	65.02	2.54	2.56	
R	4.19	4.44	0.165	0.175	
S1	6.22	BSC	0.245 BSC		
S2	3.94	BSC	0.15	5 BSC	

NOTES:

- 1. The case outline Z was originally designed using the inch-pound units of measurement, in the event of conflict between the metric and inch-pound units, the inch-pound units shall take precedence.

 2. Unless otherwise specified, the tolerance is ±.01 for two place decimals and ±.005 for three place decimals.
- 3. Device weight: 55 grams maximum.

FIGURE 1. Case outline(s) - continued.

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Device type	01
Case outlines	X and Z
Terminal number	Terminal symbol
1	Positive input
2	Inhibit
3	Sense return
4	Output common
5	Positive output
6	Positive sense
7	Case ground
8	Case ground
9	Sync input
10	Input common

FIGURE 2. Terminal connections.

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TABLE II. Electrical test requirements.

MIL-PRF-38534 test requirements	Subgroups (in accordance with MIL-PRF-38534, group A test table)
Interim electrical parameters	
Final electrical parameters	1*, 2, 3, 4, 5, 6
Group A test requirements	1, 2, 3, 4, 5, 6
Group C end-point electrical parameters	1
MIL-STD-883, group E end-point electrical parameters for RHA devices	Subgroups** (in accordance with method 5005, group A test table)

* PDA applies to subgroup 1.

- 4.2 Screening. Screening shall be in accordance with MIL-PRF-38534. The following additional criteria shall apply:
 - a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to either DSCC-VA or the acquiring activity upon request. Also, the test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.
 - (2) T_{Δ} as specified in accordance with table I of method 1015 of MIL-STD-883.
 - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.
- 4.3 <u>Conformance and periodic inspections</u>. Conformance inspection (CI) and periodic inspection (PI) shall be in accordance with MIL-PRF-38534 and as specified herein.
 - 4.3.1 Group A inspection (CI). Group A inspection shall be in accordance with MIL-PRF-38534 and as follows:
 - a. Tests shall be as specified in table II herein.
 - b. Subgroups 7, 8, 9, 10, and 11 shall be omitted.
 - 4.3.2 Group B inspection (PI). Group B inspection shall be in accordance with MIL-PRF-38534.

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^{**} When applicable to this standard microcircuit drawing, the subgroups shall be defined.

- 4.3.3 Group C inspection (PI). Group C inspection shall be in accordance with MIL-PRF-38534 and as follows:
 - a. End-point electrical parameters shall be as specified in table II herein.
 - b. Steady-state life test, method 1005 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to either DSCC-VA or the acquiring activity upon request. Also, the test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.
 - (2) TA as specified in accordance with table I of method 1005 of MIL-STD-883.
 - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.
- 4.3.4 Group D inspection (PI). Group D inspection shall be in accordance with MIL-PRF-38534.
- 4.3.5 <u>Group E inspection</u>. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein). RHA levels shall be M, D, R, and H. RHA quality conformance inspection sample tests shall be performed at the RHA level specified in the acquisition document.
 - a. RHA tests for levels M, D, R, and H shall be performed through each level to determine at what levels the devices meet the RHA requirements. These RHA tests shall be performed for initial qualification and after design or process changes which may affect the RHA performance of the device.
 - b. End-point electrical parameters shall be as specified in table II herein.
 - c. Prior to total dose irradiation, each selected sample shall be assembled in its qualified package. It shall pass the specified group A electrical parameters in table I for subgroups specified in table II herein.
 - d. The devices shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38534 for RHA level being tested, and meet the postirradiation end-point electrical parameter limits as defined in table I at T_A = +25°C ±5 percent, after exposure.
 - e. Prior to and during total dose irradiation testing, the devices shall be biased to establish a worst case condition as specified in the radiation exposure circuit.
 - For device classes H and K, subgroups 1 and 2 in table V, method 5005 of MIL-STD-883 shall be tested as appropriate for device construction.
 - g. When specified in the purchase order or contract, a copy of the RHA delta limits shall be supplied.
 - 5. PACKAGING
 - 5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38534.
 - 6. NOTES
- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.
- 6.2 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-973 using DD Form 1692, Engineering Change Proposal.

STANDARD MICROCIRCUIT DRAWING DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000	SIZE A		5962-93070
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6.4 <u>Record of users</u> . Military and industrial users shall inform Defense Supply Center Columbus when a system application requires configuration control and the applicable SMD. DSCC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DSCC-VA, telephone (614) 692-0526.			
6.5 <u>Comments</u> . Comments on this drawing should be directed to DSCC-VA, Columbus, Ohio 43216-5000, or telephone (614) 692-0512.			
6.6 Sources of supply. Sources of supply are listed in QML-38534. The vendors listed in QML-38534 have submitted a certificate of compliance (see 3.7 herein) to DSCC-VA and have agreed to this drawing.			
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STANDARD MICROSIDE IN THE PROPERTY OF THE PROP	SIZE A		5962-93070
MICROCIRCUIT DRAWING DEFENSE SUPPLY CENTER COLUMBUS		REVISION LEVEL	SHEET
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STANDARD MICROCIRCUIT DRAWING SOURCE APPROVAL BULLETIN

DATE: 98-07-22

Approved sources of supply for SMD 5962-93070 are listed below for immediate acquisition only and shall be added to QML-38534 during the next revision. QML-38534 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DSCC-VA. This bulletin is superseded by the next dated revision of QML-38534.

Standard	Vendor	Vendor
microcircuit drawing	CAGE	similar
PIN <u>1</u> /	number	PIN <u>2</u> /
5962-9307001HXA	50821	MTR2815S/883
5962-9307001HXC	50821	MTR2815S/883
5962-9307001HZA	50821	MTR2815SF/883
5962-9307001HZC	50821	MTR2815SF/883

- 1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.
- 2/ <u>Caution</u>. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE _number_

50821

Vendor name and address

Interpoint Corporation 10301 Willows Road Redmond, WA 98052

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in this information bulletin.

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